

ISO/TTA 6:2007-10 (E)

Code of practice for creep/fatigue testing of cracked components

Contents		Page
1	EXECUTIVE SUMMARY	1
2	SCOPE.....	1
3	SPECIFIC OBJECTIVES.....	2
4	INTRODUCTION.....	2
4.1	Background to VAMAS Creep Crack Growth Initiatives	3
4.2	Background to Industrial needs for validated Test Data	3
4.3	Relevance of Testing Methods to Life Assessment Codes	4
4.3.1	Background to Life Assessment Codes	4
4.3.2	Relation between laboratory tests and Component Assessment Codes	5
4.3.3	Factors involved in the development of assessment codes	5
4.4	Requirements for the VAMAS TWA 25 CoP	6
4.5	ISO requirements	6
4.5.1	ISO Technology Trend Assessment (ISO/TTA).....	7
5	Acknowledgements	7
5.1	List of participants in VAMAS TWS25.....	7
6	NOMENCLATURE AND ABBREVIATIONS.....	8
6.1	Nomenclatures	8
6.2	Listing of abbreviations.....	9
7	DESCRIPTION OF CREEP AND FATIGUE CRACKING.....	10
7.1	Failure due Creep Crack Growth (CCG).....	10
7.2	Creep Crack Initiation (CCI)	10
7.3	Transient crack growth conditions	10
7.4	Steady state Creep Cracking (CCG).....	10
7.5	Fatigue and Creep/Fatigue Crack Growth (FCG and CFCG)	11
7.5.1	Failure due to fatigue.....	11
7.5.2	Creep/Fatigue interaction.....	11
7.6	Factors affecting CCI, CCG and CFCG	11
7.6.1	Creep properties	11
7.6.2	Metallurgical effects.....	12
7.6.3	Presence of residual stress fields	12
7.6.4	Aggressive environments	12
7.6.5	Anisotropic and inhomogeneous material characteristics	12
8	TEST METHODS	13
8.1	Overview	13
8.2	Test Geometries	13
8.3	Experimental Test Methods	14
8.3.1	Material procurement.....	14
8.3.2	Specimen selection.....	14
8.3.3	Crack-plane orientation	14
8.3.4	Specimen machining	14
8.3.5	Specific size requirements.....	15
8.3.6	Specific side-grooving requirements.....	15
8.3.7	Shape of the crack front.....	15
8.3.8	Pre-cracking to introduce a sharp flat crack front	15
8.3.9	Pre-cracking for CCI tests	15
8.3.10	Crack length measurements	16
8.3.11	The use of Potential Drop (PD)	16
8.3.12	Preparing the specimens for PD leads	16
8.3.13	Specimen setup.....	16

8.3.14	Loading and creep displacement measurements	16
8.3.15	Displacement gauge	17
8.3.16	Heating of the specimens	17
8.3.17	Initial pre-load	17
8.3.18	Monitoring the temperature	17
8.3.19	Unplanned temperature excursions	17
8.3.20	Initial pre-load	18
8.3.21	Specimen loading	18
8.4	Data Collection	18
8.4.1	Detailed test and data monitoring	18
8.4.2	Data logging	18
8.4.3	Displacement measurements	18
8.5	Post-Test Measurements	19
8.5.1	Measurement of the final crack front	19
8.5.2	Crack tip bowing	19
8.5.3	Crack extension criteria	19
8.5.4	Crack deviation criteria	19
8.6	Recommended Minimum Number and Duration for Tests	20
8.6.1	Batch to batch variability	20
8.6.2	Minimum test requirements	20
8.6.3	Single point data per test	21
8.6.4	Multiple points data per test	21
8.6.5	Test duration requirements	21
8.7	Sensitivity and Accuracy Limits of the Results	21
8.7.1	Effects of data variability on correlation for FCG, CCG and CCI	21
8.8	Preparation of Test Data	22
8.8.1	Data collection	22
8.8.2	Time at which the test should be stopped	22
8.8.3	Smoothing the PD output data	22
8.8.4	Deriving the crack length from the PD output	22
8.8.5	Recommended number of data points	23
8.8.6	Calculating cracking and displacement rates	23
9	DATA ANALYSIS PROCEDURES	23
9.1	Choosing an appropriate CCI or CCG rate Correlating Parameter	23
9.1.1	Choice of parameter for correlating CCG	23
9.1.2	Choice of the C^* term for CCG rate	23
9.1.3	Choice of parameter for CCI	24
9.2	Definitions for the relevant Fracture Mechanics Parameters	24
9.2.1	Stress intensity factor, K	24
9.2.2	J-integral	24
9.2.3	The C^* parameter	24
9.2.4	Creep zone	25
9.2.5	Steady state creep	25
9.2.6	The C_t parameter	26
9.2.7	Small-scale creep	26
9.2.8	Interpretation of C^* parameter	26
9.2.9	Time Dependant Failure Assessment Diagram (TDFAD) for CCI	26
9.2.10	The Q^* Parameter	27
9.3	Criteria for Validity Checks of C^* and K	27
9.3.1	Check for validity of C^*	27
9.3.2	Components of displacement rates	27
9.3.3	Validity criteria for C^* for highly ductile materials	28
9.3.4	Validity criteria for creep brittle materials	29
9.3.5	Transition time criteria for C^*	29
10	REPORTING PROCEDURES	30
10.1	Details of test information to be reported	30
10.1.1	Report of findings	30
10.1.2	Pedigree of the material	30
10.1.3	Material properties to be logged	30

10.1.4	Test machine description.....	30
10.1.5	Details of starter crack	30
10.1.6	Details for loading.....	30
10.1.7	Report of data analysis.....	30
10.1.8	Plots of data.....	31
10.1.9	Tabulation of results.....	31
10.1.10	Photographic/micrographic evidence.....	31
10.1.11	Treatment of anomalous data.....	31
11	CORRELATING CRACK GROWTH USING FRACTURE MECHANICS.....	31
11.1	CCG rate analysis	31
11.2	Crack Initiation (CCI) Analysis.....	32
11.3	FCG rate Analysis	32
11.4	Creep/fatigue crack growth rate analysis.....	33
12	Methods for Calculating the C* Parameter.....	33
12.1	Experimental Estimates of C*	33
12.2	Reference Stress Method of Estimating C*.....	34
13	APPENDIX I.....	36
13.1	Test Specimen Geometries.....	36
13.2	Geometry Definitions for Laboratory Specimens.....	36
14	SPECIMEN FRACTURE MECHANICS PARAMETER SOLUTIONS.....	38
14.1	Stress Intensity Factor K	38
14.2	Solutions for the Y function.....	38
14.2.1	Y factor for C(T).....	39
14.2.2	Y factor for CS(T).....	39
14.2.3	Y factor for SEN(T).....	39
14.2.4	Y factor for SEN(B) (3 Point Bend Specimen).....	39
14.2.5	Y factor for DEN(T).....	40
14.2.6	Y factor for M(T).....	40
14.3	C* Solutions.....	40
14.4	Reference Stress (σ_{ref}) Solutions.....	41
14.4.1	σ_{ref} for C(T).....	41
14.4.2	σ_{ref} for CS(T).....	42
14.4.3	σ_{ref} for SEN(T).....	42
14.4.4	σ_{ref} for SEN(B) (3 Point Bend Specimen).....	42
14.4.5	σ_{ref} for DEN(T).....	42
14.4.6	σ_{ref} for M(T).....	43
14.5	η Functions for cracked geometries.....	43
14.5.1	Nomenclature (see Figure A.1.3).....	43
14.5.2	Solutions for creep crack growth parameter, C*.....	44
14.5.3	Best fit solutions of η from finite element calculations.....	45
14.5.4	Choice of η for evaluating C* for material CCI and CCG properties.....	45
14.5.5	Choice of η for evaluating C* in life assessment.....	45
14.6	η Function Equations.....	46
14.6.1	η functions for C(T).....	46
14.6.2	η functions for CS(T).....	46
14.6.3	η functions for SEN(T).....	46
14.6.4	η functions for SEN(B) — 3PB.....	47
14.6.5	η functions for DEN(T).....	47
14.6.6	η functions for M(T).....	47
14.7	Table for η^{LLD}	49
14.8	Table for η^{CMOD}	50
14.9	Geometry Definitions for 'Feature' Type Specimens.....	51
14.9.1	Details form Pipe, Plate and Notched bar 'feature specimens'.....	51
14.10	Fracture Mechanics Functions for Feature Components.....	52
14.10.1	K solutions for pipes and plates.....	52
14.10.2	Reference stress solutions for pipes.....	53
14.10.3	Reference stress solutions for plates.....	53

14.10.4	Stress intensity factor K for the round notch bar	54
14.10.5	C* parameter for the notched bar.....	54
15	APPENDIX II :(TDFAD) K_{mat}^c approach for CCI.....	55
15.1	Introduction	55
15.2	Nomenclature	55
15.3	Failure Assessment Diagram	56
15.4	Materials Data Requirements	57
16	APPENDIX III: The Q* Parameter	61
16.1	Symbols and Designations.....	61
16.2	Scope	62
16.3	Specimen Geometry	62
16.4	Guideline for Calculation of the Q* parameter.....	62
16.4.1	Crack Growth Analysis	62
16.4.2	Crack initiation Analysis	63
17	APPENDIX IV: Local CTOD Approach	64
17.1	Crack Tip Opening Displacement (CTOD).....	64
18	APPENDIX V: Further Detailed Advice on Testing	66
18.1	Advice on Testing and Machine Specification	66
18.2	Loading Machine.....	66
18.3	Machine Tolerances	66
18.4	Grips.....	66
18.5	Alignment	66
18.6	Specimen Dimensional Measurement	67
18.7	Specimen Preparation	67
18.8	Permissible Temperature Deviation.....	67
18.9	Temperature Hold-time before start of Test.....	67
18.10	Thermocouple Junction and Wiring	67
18.11	Thermocouple Attachment	68
18.12	Verification of Thermocouple	68
18.13	Application of Load	68
18.14	Loading Precautions	68
18.15	Displacement Measurement	68
18.16	Apparatus for Crack Size Measurement.....	69
18.17	Potential Difference (PD) Performance	69
18.18	Specimen Preparation for Electric Potential Measurement	69
18.19	Premature Test Failure	69
18.20	Recommended Method for Treating Extensive Plasticity	69
18.21	Recommended Data Reduction Techniques	70
18.21.1	Calculating the cracking and displacement rates	70
18.21.2	Method for calculating the cracking and displacement rates.....	70
18.21.3	Secant method for deriving CCG and displacement rates	70
18.21.4	Incremental polynomial method to derive CCG and displacement rates	70
18.21.5	Calculating crack length	71
18.21.6	Voltage versus crack length relation	71
19	REFERENCES – Related International Standards and Codes	72
20	REFERENCES – Relevant Publications.....	74